



Product/Process Change Notice - PCN 08_0152 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of receiving this notification. ADI contact information is listed below.

Revision Description*:

Initial Release

PCN Title: SSM2166, New Design and Conversion to new wafer fabrication process

Publication Date: 24-Mar-2009

Samples Available Date: 08-Dec-2008

Effectivity Date: 08-Dec-2008 *(the earliest date that a customer could expect to receive changed material)*

Description Of Change

- 1) Process Changed from ECL to HVBP2
- 2) Fab location change from ADI Santa Clara CA, to ADI Limerick, Ireland
- 3) Wafer Size Changed from 4" to 8"
- 4) Circuit layout and topology changed to meet new process design rules and existing product performance criteria.
- 5) Requires changes to external passive component values (vs previous die revision) to achieve similar output response vs input signals.

Reason For Change

- 1) Product was originally designed and manufactured on the ECL technology platform which was obsoleted with the Analog Device closure of the 4" wafer Fab facility in Santa Clara CA.
- 2) The new die provides for ongoing manufacture and supply of SSM2166 to existing and new customers
- 3) Re-design of the product was required to allow manufacture using the new fab process.

Anticipated impact of the change (positive or negative) on fit, form, function & reliability

Customers using the previous version of SSM2166 will need to change external passive component values to achieve similar I/O response when using the new die version. Recommended external component values for the new version are given in the revised datasheet rev D or later.

Product Identification *(this section will describe how to identify the changed material)*

An "A" Identifier has been added to the part name on the top mark. (See Examples of top mark below)

PB-Free
Top #1: SSM
Top #2: 2166A
Top #3: #

SnPb
Top #1: SSM
Top #2: 2166A
Top #3:

Summary of Supporting Information

Qualification was performed per ADI0012. Reliability Report 6956 - SSM2166 Die Revision is attached

Comments

Final Die Revision was released in July of 2008. This was a follow-up notification of change. Customers with active backlog and/or recent buying history were contacted during the redesign process, prior to shipment of the new die revision.

Supporting Documents

Attachment 1: ADI_PCN_08_0152_Rev_-_Reliability Report 6956.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Parts - Generic Number / Material Number (6)

SSM2166 / SSM2166S	SSM2166 / SSM2166S-REEL	SSM2166 / SSM2166S-REEL7	SSM2166 / SSM2166SZ	SSM2166 / SSM2166SZ-REEL	SSM2166 / SSM2166SZ-REEL7
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Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	24-Mar-2009	Initial Release

Analog Devices, Inc. Proprietary Information

DocId:579 Parent DocId:None